

NITED STATES PATENT AND TRADEMARK OFFICE

Applicants:

T.R. Cundiff et al.

Attorney Docket No.: BOCO117190

Application No.: 09/826,535

Group Art Unit: 1772

Filed:

April 4, 2001

Title:

RESIN TRANSFER MOLDING PROCESS

INFORMATION DISCLOSURE STATEMENT

Seattle, Washington 98101

August 8, 2001

TO THE COMMISSIONER FOR PATENTS:

Applicants are aware of the information listed in the attached form that may be material to the prosecution of the above-identified patent application.

- <u>1.</u> This application relies, under 35 U.S.C. § 120, on the earlier filing date of prior Application No. 09/115,568, filed July 14, 1998. The references listed on the attached form were submitted to and/or cited by the Patent and Trademark Office in this prior application and, therefore, are not required to be provided in this application.
- 2. Pursuant to 37 C.F.R. § 1.97(b), this Information Disclosure Statement is being filed within three months of the filing date of the national application (other than a CPA), within three months of the date of entry of the national stage as set forth in 37 C.F.R. § 1.491 in an international application, before the mailing date of a first Office Action on the merits, or before the mailing date of a first Office Action after the filing of an RCE.
- commissioner is hereby authorized to charge any fees under 37 C.F.R. 3. \$\langle 1.16, \rangle 1.17 and 1.18 which may be required during the entire pendency of the application, or credit any overpayment, to Deposit Account No. 03-1740. This authorization also hereby includes a request for any extensions of time of the

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appropriate length required upon the filing of any reply during the entire prosecution of this application. A copy of this document is enclosed.

Respectfully submitted,

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I hereby certify that this correspondence is being deposited with the U.S. Postal Service in a sealed envelope as first class mail with postage thereon fully prepaid and addressed to the Commissioner for Patents, Washington, D.C. 20231, on the below date.

Date

8/8/01

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